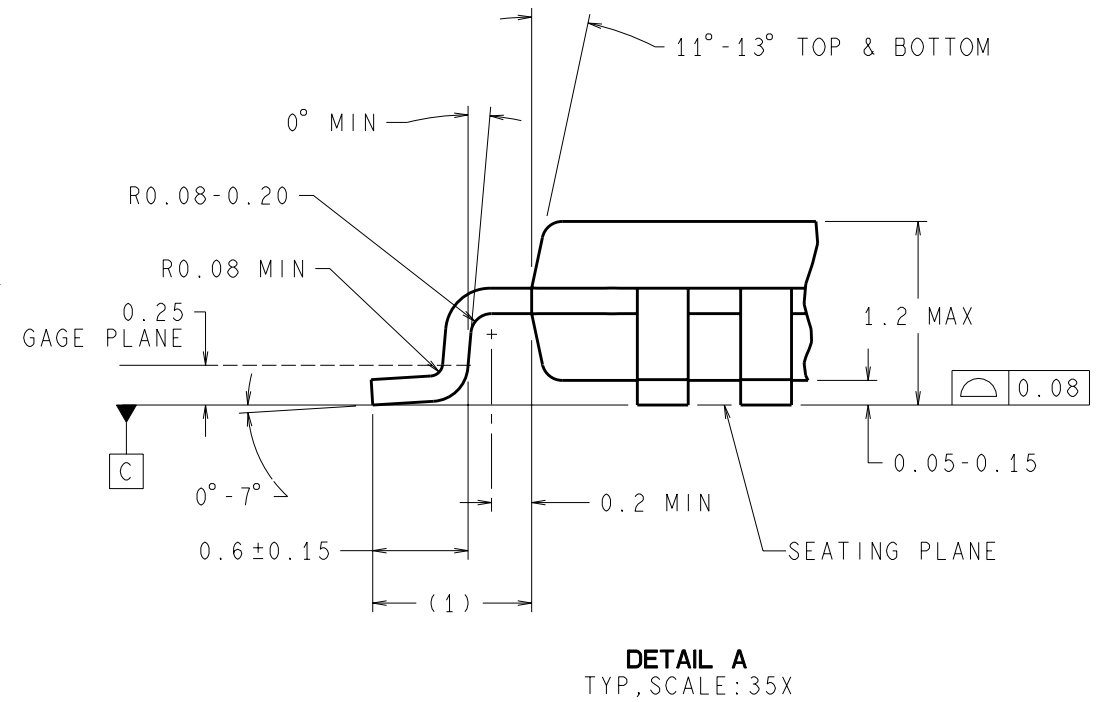
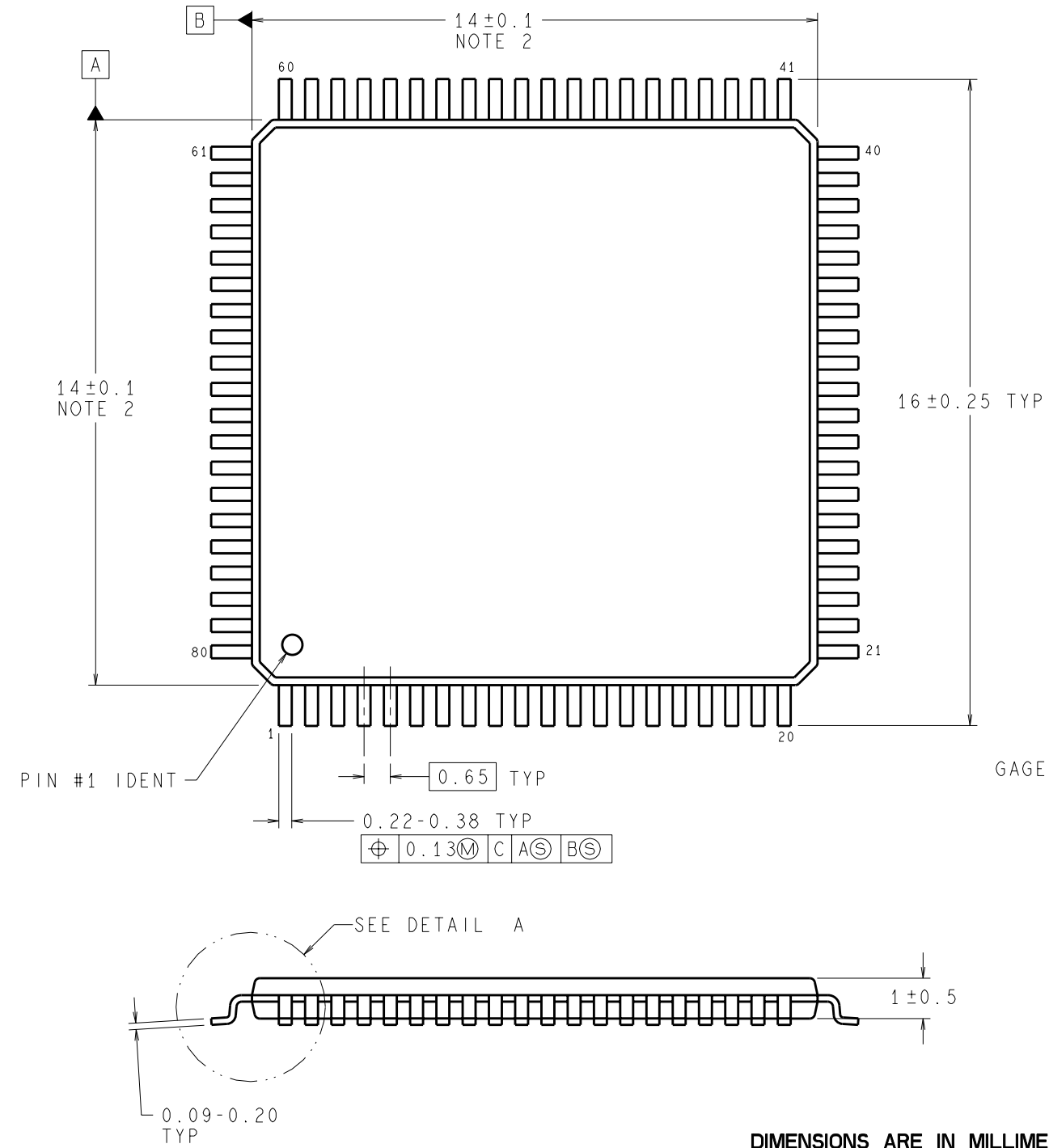


REVISIONS				
LTR	DESCRIPTION	E.C.N.	DATE	BY/APP'D
A	RELEASE TO DOCUMENT CONTROL.	11076	08/07/1995	DEG/HJK
B	TITLE: TOFP WAS PQFP; UPDATE NOTE 3; ADD GEOMETRIC TOLERANCE	12317	12/02/1999	ACS/MS/RW



DIMENSIONS ARE IN MILLIMETERS

- NOTES: UNLESS OTHERWISE SPECIFIED
- STANDARD LEAD FINISH:
7.62 MICROMETERS MINIMUM SOLDER PLATING (85/15)
THICKNESS ON COPPER.
 - DIMENSION DOES NOT INCLUDE MOLD PROTRUSION.
MAXIMUM ALLOWABLE MOLD PROTRUSION 0.25mm PER SIDE.
 - REFERENCE JEDEC REGISTRATION MS-026, VARIATION AEC,
DATED FEB 1999.

APPROVALS		DATE		 National Semiconductor 2900 Semiconductor Dr., Santa Clara, CA 95052-8090	
DRAWN D.E. Grady		08/07/1995			
DFTG. CHK. THANH LEQUANG		12/07/1999			
ENGR. CHK. RANDALL WALBERG		12/07/1999		TOFP, JEDEC METRIC, 14 X 14 X 1.0mm, 80 LEAD	
 PROJECTION INCH [MM]		SCALE N/A	SIZE C		
FORMERLY:				SHEET 1 of 1	